

SWK9435

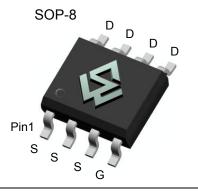
30V Single P-Channel Enhancement-Mode MOSFET

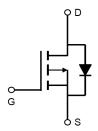
General Description

- Low gate charge.
- Uses advanced trench process technology.
- Use in PWM applications

Product Summary

- BV_{DSS} -30V
- $R_{DS(on)}$ @VGS = 10V < 60m Ω
- $R_{DS(on)}$ @VGS = 4.5V < 90m Ω





Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

Parameter	Symbol	Maximum	Units
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Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current (T _A =25°C)		-5.3	Α
Drain Current (T _A =75°C)	I _D	-2.8	Α
Pulsed Drain Current ^a	I _{DM}	-18	Α
Power Dissipation ^b (T _A =25°C)		2.5	W
Power Dissipation ^b (T _A =75°C)	P _D	1.0	W
Junction and Storage Temperature Range	$T_{J,}T_{STG}$	-55 ~ +150	°C

Thermal Characteristics

Parameter	Symbol	Maximum	Units	
Junction-to-Ambient ^a (t ≤ 10s)	0	50	°C/W	
Junction-to-Ambient ^{a,d} (Steady-State)	$R_{ heta JA}$	90	°C/W	
Junction-to-Lead (Steady-State)	$R_{ heta JL}$	25	°C/W	

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Symbol	Parameter	Conditions	Min	Тур	Max	Units
Off Char	acteristics				•	
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = -250uA$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -24V , V _{GS} = 0V			-1	uA
I_{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA
On Chara	acteristics					
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = -250uA$	-1		-2.5	V
В	Drain-Source	$V_{GS} = -10V$, $I_D = -5.3A$			60	mΩ
R _{DS(ON))}	On-State Resistance	$V_{GS} = -4.5V$, $I_D = -4.5A$			90	mΩ
9 FS	Forward Transconductance	$V_{DS} = -10V$, $I_{D} = -5.3A$		18		S
Drain-So	urce Diode Characteristics					
V_{SD}	Diode Forward Voltage	$V_{GS} = 0V$, $I_{S} = -1.0A$			-1.3	V
Is	Maximum Body-Diode Continuous	num Body-Diode Continuous Current			-2.0	Α
Dynamic	Characteristics					
C_{iss}	Input Capacitance	V _{DS} = -15V , V _{GS} = 0V f = 1.0MHz		553		pF
C_{oss}	Output Capacitance			93		pF
C_{rss}	Reverse Transfer Capacitance			63		pF
Switchin	g Characteristics					
Q_{g}	Total Gate Charge			12		nC
Q_gs	Gate-Source Charge	$V_{DS} = -15V$, $I_{D} = -5.3A$ $V_{GS} = -10V$		4		nC
Q_{gd}	Gate-Drain Charge			5		nC
t _{D(ON})	Turn-On Delay Time	$V_{DD} = -15V$, $ID = -1A$ $V_{GS} = -10 V$ $R_{GEN} = -6 \text{ ohm}$		14		ns
t _r	Turn-On Rise Time			5		ns
$t_{D(OFF)}$	Turn-Off Delay Time			20		ns
t _f	Turn-Off Fall Time			6		ns

a. Repetitive rating, Pulse width limited by junction temperature $T_{J(MAX)}$ =150 °C. Ratings are based on low frequency and duty cycles to keep initial T_J =25 °C

b. The power dissipation P_D is based on $T_{J(MAX)}$ =150 °C , using \leq 10s junction-to-ambient thermal resistance.

c. The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25$ °C. The value in any given application depends on the user's specific board design.

d. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.